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Details

Product Status	Active
Core Processor	12V1
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, IrDA, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	86
Program Memory Size	240KB (240K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	11K x 8
Voltage - Supply (Vcc/Vdd)	3.13V ~ 5.5V
Data Converters	A/D 16x12b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/s9s12ga240f0vll

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	Function <lowestpriorityhighest></lowestpriorityhighest>				Power	Internal P Resisto	Pull r	
Package Pin	Pin	2nd Func.	3rd Func.	4th Func	5th Func	Supply	CTRL	Reset State
1	PJ6	KWJ6	SCK2	—	_	V _{DDX}	PERJ/PPSJ	Up
2	PJ5	KWJ5	MOSI2	—	_	V _{DDX}	PERJ/PPSJ	Up
3	PJ4	KWJ4	MISO2	—	_	V _{DDX}	PERJ/PPSJ	Up
4	RESET	_	—	—	_	V _{DDX}	PULLUF	2
5	VDDX	_	—	—	_	—	_	—
6	VDDR	_	—	—	_	—	_	—
7	VSSX	_	—	—	_	—	_	—
8	PE0 ¹	EXTAL	—	—	_	V _{DDX}	PUCR/PDPEE	Down
9	VSS	_	—	—	_	—	_	—
10	PE1 ¹	XTAL	—	—	_	V _{DDX}	PUCR/PDPEE	Down
11	TEST	_	—	—	_	N.A.	RESET pin	Down
12	PJ0	KWJ0	MISO1	—	_	V _{DDX}	PERJ/PPSJ	Up
13	PJ1	KWJ1	MOSI1	—	_	V _{DDX}	PERJ/PPSJ	Up
14	PJ2	KWJ2	SCK1	—	_	V _{DDX}	PERJ/PPSJ	Up
15	PJ3	KWJ3	SS1	—	_	V _{DDX}	PERJ/PPSJ	Up
16	BKGD	MODC	—	—	_	V _{DDX}	PUCR/BKPUE	Up
17	PP0	KWP0	ETRIG0	API_EXTC LK	PWM0	V _{DDX}	PERP/PPSP	Disabled
18	PP1	KWP1	ETRIG1	ECLKX2	PWM1	V _{DDX}	PERP/PPSP	Disabled
19	PP2	KWP2	ETRIG2	PWM2	_	V _{DDX}	PERP/PPSP	Disabled
20	PP3	KWP3	ETRIG3	PWM3	_	V _{DDX}	PERP/PPSP	Disabled
21	PP4	KWP4	PWM4	—	_	V _{DDX}	PERP/PPSP	Disabled
22	PP5	KWP5	PWM5	—	_	V _{DDX}	PERP/PPSP	Disabled
23	PP6	KWP6	PWM6	—	_	V _{DDX}	PERP/PPSP	Disabled
24	PP7	KWP7	PWM7	—	_	V _{DDX}	PERP/PPSP	Disabled
25	PT7	IOC7	_	_	_	V _{DDX}	PERT/PPST	Disabled
26	PT6	IOC6	—	—	_	V _{DDX}	PERT/PPST	Disabled
27	PT5	IOC5	—	—		V _{DDX}	PERT/PPST	Disabled

Table 1-24. 64-Pin LQFP Pinout for S12GA96 and S12GA128

	Function <lowestpriorityhighest></lowestpriorityhighest>					Internal Pull Resistor	
Wire Bond Die Pad	Pin	2nd Func.	3rd Func.	4th Func.	Supply	CTRL	Reset State
27	PB2	ECLKX2	—	—	V _{DDX}	PUCR/PUPBE	Disabled
28	PB3	—	—	—	V _{DDX}	PUCR/PUPBE	Disabled
29	PP0	KWP0	ETRIG0	PWM0	V _{DDX}	PERP/PPSP	Disabled
30	PP1	KWP1	ETRIG1	PWM1	V _{DDX}	PERP/PPSP	Disabled
31	PP2	KWP2	ETRIG2	PWM2	V _{DDX}	PERP/PPSP	Disabled
32	PP3	KWP3	ETRIG3	PWM3	V _{DDX}	PERP/PPSP	Disabled
33	PP4	KWP4	PWM4	_	V _{DDX}	PERP/PPSP	Disabled
34	PP5	KWP5	PWM5	—	V _{DDX}	PERP/PPSP	Disabled
35	PP6	KWP6	PWM6	—	V _{DDX}	PERP/PPSP	Disabled
36	PP7	KWP7	PWM7	—	V _{DDX}	PERP/PPSP	Disabled
37	VDDX3	—	—	—	—	_	_
38	VSSX3	—	—	—	—	_	_
39	PT7	IOC7	_		V _{DDX}	PERT/PPST	Disabled
40	PT6	IOC6	—	—	V _{DDX}	PERT/PPST	Disabled
41	PT5	IOC5	—	—	V _{DDX}	PERT/PPST	Disabled
42	PT4	IOC4	_	_	V _{DDX}	PERT/PPST	Disabled
43	PT3	IOC3	—	—	V _{DDX}	PERT/PPST	Disabled
44	PT2	IOC2	_	_	V _{DDX}	PERT/PPST	Disabled
45	PT1	IOC1	—	—	V _{DDX}	PERT/PPST	Disabled
46	PT0	IOC0	—	—	V _{DDX}	PERT/PPST	Disabled
47	PB4	ĪRQ	—	—	V _{DDX}	PUCR/PUPBE	Disabled
48	PB5	XIRQ	—	—	V _{DDX}	PUCR/PUPBE	Disabled
49	PB6	—	—	—	V _{DDX}	PUCR/PUPBE	Disabled
50	PB7	—	—	—	V _{DDX}	PUCR/PUPBE	Disabled
51	PC0	—	—	—	V _{DDA}	PUCR/PUPCE	Disabled
52	PC1	—	_	—	V _{DDA}	PUCR/PUPCE	Disabled
53	PC2	—	—	—	V _{DDA}	PUCR/PUPCE	Disabled
54	PC3	—	—	—	V _{DDA}	PUCR/PUPCE	Disabled
55	PAD0	KWAD0	AN0	—	V _{DDA}	PER1AD/PPS1AD	Disabled

Table 2-40. PTS Register Field Descriptions

Field	Description
7-0 PTS	Port S general-purpose input/output data —Data Register When not used with an alternative signal, the associated pin can be used as general-purpose I/O. In general-purpose output mode the port data register bit value is driven to the pin. If the associated data direction bit is set to 1, a read returns the value of the port data register bit, otherwise the buffered pin input state is read.

2.4.3.21 Port S Input Register (PTIS)



Table 2-41. PTIS Register Field Descriptions

Field	Description
7-0	Port S input data —
PTIS	A read always returns the buffered input state of the associated pin. It can be used to detect overload or short circuit conditions on output pins.

2.4.3.22 Port S Data Direction Register (DDRS)

Address 0x024A Access: User read/write¹ 7 6 5 3 2 0 4 1 R DDRS7 DDRS6 DDRS5 DDRS4 DDRS3 DDRS2 DDRS1 DDRS0 W 0 0 0 0 0 0 0 0 Reset Figure 2-23. Port S Data Direction Register (DDRS)

¹ Read: Anytime Write: Anytime

Field	Description
7-0 PERP	 Port P pull device enable—Enable pull device on input pin This bit controls whether a pull device on the associated port input pin is active. If a pin is used as output this bit has no effect. The polarity is selected by the related polarity select register bit. 1 Pull device enabled 0 Pull device disabled

Table 2-64. PERP Register Field Descriptions

2.4.3.38 Port P Polarity Select Register (PPSP)



Figure 2-39. Port P Polarity Select Register (PPSP)

¹ Read: Anytime

Write: Anytime

Table 2-65. PPSP Register Field Descriptions

Field	Description
7-0 PPSP	Port P pull device select —Configure pull device and pin interrupt edge polarity on input pin This bit selects a pullup or a pulldown device if enabled on the associated port input pin. This bit also selects the polarity of the active pin interrupt edge.
	1 Pulldown device selected; rising edge selected 0 Pullup device selected; falling edge selected

Figure 10-2 shows a block diagram of the XOSCLCP.



Figure 10-2. XOSCLCP Block Diagram

10.2 Signal Description

This section lists and describes the signals that connect off chip.

10.2.1 RESET

Pin $\overline{\text{RESET}}$ is an active-low bidirectional pin. As an input it initializes the MCU asynchronously to a known start-up state. As an open-drain output it indicates that an MCU-internal reset has been triggered.

10.2.2 EXTAL and XTAL

These pins provide the interface for a crystal to control the internal clock generator circuitry. EXTAL is the input to the crystal oscillator amplifier. XTAL is the output of the crystal oscillator amplifier. If XOSCLCP is enabled, the MCU internal OSCCLK_LCP is derived from the EXTAL input frequency. If OSCE=0, the EXTAL pin is pulled down by an internal resistor of approximately 200 k Ω and the XTAL pin is pulled down by an internal resistor of approximately 200 k Ω .

SMP2	SMP1	SMP0	Sample Time in Number of ATD Clock Cycles
1	1	1	24

Table 12-13. Sample Time Select

12.3.2.6 ATD Control Register 5 (ATDCTL5)

Writes to this register will abort current conversion sequence and start a new conversion sequence. If the external trigger function is enabled (ETRIGE=1) an initial write to ATDCTL5 is required to allow starting of a conversion sequence which will then occur on each trigger event. Start of conversion means the beginning of the sampling phase.

Module Base + 0x0005



Figure 12-8. ATD Control Register 5 (ATDCTL5)

Read: Anytime

Write: Anytime

Table 12-14. ATDCTL5 Field Descriptions

Field	Description
6 SC	 Special Channel Conversion Bit — If this bit is set, then special channel conversion can be selected using CD, CC, CB and CA of ATDCTL5. Table 12-15 lists the coding. O Special channel conversions disabled 1 Special channel conversions enabled
5 SCAN	 Continuous Conversion Sequence Mode — This bit selects whether conversion sequences are performed continuously or only once. If the external trigger function is enabled (ETRIGE=1) setting this bit has no effect, thus the external trigger always starts a single conversion sequence. 0 Single conversion sequence 1 Continuous conversion sequences (scan mode)

Field	Description
3–0 CC[3:0]	Conversion Counter — These 4 read-only bits are the binary value of the conversion counter. The conversion counter points to the result register that will receive the result of the current conversion. E.g. CC3=0, CC2=1, CC1=1, CC0=0 indicates that the result of the current conversion will be in ATD Result Register 6. If in non-FIFO mode (FIFO=0) the conversion counter is initialized to zero at the beginning and end of the conversion sequence. If in FIFO mode (FIFO=1) the register counter is not initialized. The conversion counter wraps around when its maximum value is reached.

14.3.2.8 ATD Compare Enable Register (ATDCMPE)

Writes to this register will abort current conversion sequence.

Read: Anytime

Write: Anytime

Module Base + 0x0008





Table 14-17. ATDCMPE Field Descriptions

Field	Description
11–0 CMPE[11:0]	Compare Enable for Conversion Number <i>n</i> (<i>n</i> = 11, 10, 9, 8, 7, 6, 5, 4, 3, 2, 1, 0) of a Sequence (<i>n</i> conversion <i>number</i> , <i>NOT channel number</i> !) — These bits enable automatic compare of conversion results individually for conversions of a sequence. The sense of each comparison is determined by the CMPHT[<i>n</i>] bit in the ATDCMPHT register.
	For each conversion number with CMPE[<i>n</i>]=1 do the following: 1) Write compare value to ATDDR <i>n</i> result register 2) Write compare operator with CMPHT[<i>n</i>] in ATDCPMHT register
	 CCF[<i>n</i>] in ATDSTAT2 register will flag individual success of any comparison. 0 No automatic compare 1 Automatic compare of results for conversion <i>n</i> of a sequence is enabled.

14.3.2.10 ATD Input Enable Register (ATDDIEN)

Module Base + 0x000C



Read: Anytime

Write: Anytime

Table 14-19. ATDDIEN Field Descriptions

Field	Description
11–0 IEN[11:0]	 ATD Digital Input Enable on channel x (x= 11, 10, 9, 8, 7, 6, 5, 4, 3, 2, 1, 0) — This bit controls the digital input buffer from the analog input pin (ANx) to the digital data register. 0 Disable digital input buffer to ANx pin 1 Enable digital input buffer on ANx pin. Note: Setting this bit will enable the corresponding digital input buffer continuously. If this bit is set while simultaneously using it as an analog port, there is potentially increased power consumption because the digital input buffer maybe in the linear region.

14.3.2.11 ATD Compare Higher Than Register (ATDCMPHT)

Writes to this register will abort current conversion sequence.

Read: Anytime

Write: Anytime

Module Base + 0x000E



Figure 14-13. ATD Compare Higher Than Register (ATDCMPHT)

Table 14-20. ATDCMPHT Field Descriptions

Field	Description		
11–0	Compare Operation Higher Than Enable for conversion number <i>n</i> (<i>n</i> = 11, 10, 9, 8, 7, 6, 5, 4, 3, 2, 1, 0) of		
CMPHT[11:0]	a Sequence (<i>n conversion number, NOT channel number!</i>) — This bit selects the operator for comparison		
	of conversion results.		
	0 If result of conversion <i>n</i> is lower or same than compare value in ATDDR <i>n</i> , this is flagged in ATDSTAT2		
	1 If result of conversion <i>n</i> is higher than compare value in ATDDR <i>n</i> , this is flagged in ATDSTAT2		

15.1 Introduction

The ADC10B16C is a 16-channel, 10-bit, multiplexed input successive approximation analog-to-digital converter. Refer to device electrical specifications for ATD accuracy.

15.1.1 Features

- 8-, 10-bit resolution.
- Automatic return to low power after conversion sequence
- Automatic compare with interrupt for higher than or less/equal than programmable value
- Programmable sample time.
- Left/right justified result data.
- External trigger control.
- Sequence complete interrupt.
- Analog input multiplexer for 8 analog input channels.
- Special conversions for VRH, VRL, (VRL+VRH)/2.
- 1-to-16 conversion sequence lengths.
- Continuous conversion mode.
- Multiple channel scans.
- Configurable external trigger functionality on any AD channel or any of four additional trigger inputs. The four additional trigger inputs can be chip external or internal. Refer to device specification for availability and connectivity.
- Configurable location for channel wrap around (when converting multiple channels in a sequence).

Module Base + 0x00006



Read: Anytime

Write: Anytime

NOTE

Register bits PCLKAB0 to PCLKAB7 can be written anytime. If a clock select is changed while a PWM signal is being generated, a truncated or stretched pulse can occur during the transition.

Table 19-11. PWMCLK Field Descriptions

Note: Bits related to available channels have functional significance. Writing to unavailable bits has no effect. Read from unavailable bits return a zero

Field	Description
7 PCLKAB7	 Pulse Width Channel 7 Clock A/B Select 0 Clock B or SB is the clock source for PWM channel 7, as shown in Table 19-6. 1 Clock A or SA is the clock source for PWM channel 7, as shown in Table 19-6.
6 PCLKAB6	 Pulse Width Channel 6 Clock A/B Select 0 Clock B or SB is the clock source for PWM channel 6, as shown in Table 19-6. 1 Clock A or SA is the clock source for PWM channel 6, as shown in Table 19-6.
5 PCLKAB5	 Pulse Width Channel 5 Clock A/B Select 0 Clock A or SA is the clock source for PWM channel 5, as shown in Table 19-5. 1 Clock B or SB is the clock source for PWM channel 5, as shown in Table 19-5.
4 PCLKAB4	 Pulse Width Channel 4 Clock A/B Select 0 Clock A or SA is the clock source for PWM channel 4, as shown in Table 19-5. 1 Clock B or SB is the clock source for PWM channel 4, as shown in Table 19-5.
3 PCLKAB3	 Pulse Width Channel 3 Clock A/B Select 0 Clock B or SB is the clock source for PWM channel 3, as shown in Table 19-6. 1 Clock A or SA is the clock source for PWM channel 3, as shown in Table 19-6.
2 PCLKAB2	 Pulse Width Channel 2 Clock A/B Select 0 Clock B or SB is the clock source for PWM channel 2, as shown in Table 19-6. 1 Clock A or SA is the clock source for PWM channel 2, as shown in Table 19-6.
1 PCLKAB1	 Pulse Width Channel 1 Clock A/B Select 0 Clock A or SA is the clock source for PWM channel 1, as shown in Table 19-5. 1 Clock B or SB is the clock source for PWM channel 1, as shown in Table 19-5.
0 PCLKAB0	 Pulse Width Channel 0 Clock A/B Select 0 Clock A or SA is the clock source for PWM channel 0, as shown in Table 19-5. 1 Clock B or SB is the clock source for PWM channel 0, as shown in Table 19-5.

Timer Module (TIM16B8CV3)



Figure 23-30. Detailed Timer Block Diagram

Field	Description
1 DFDIF	 Double Bit Fault Detect Interrupt Flag — The setting of the DFDIF flag indicates that a double bit fault was detected in the stored parity and data bits during a Flash array read operation or that a Flash array read operation returning invalid data was attempted on a Flash block that was under a Flash command operation.¹ The DFDIF flag is cleared by writing a 1 to DFDIF. Writing a 0 to DFDIF has no effect on DFDIF.² No double bit fault detected Double bit fault detected or a Flash array read operation returning invalid data was attempted while command running
0 SFDIF	 Single Bit Fault Detect Interrupt Flag — With the IGNSF bit in the FCNFG register clear, the SFDIF flag indicates that a single bit fault was detected in the stored parity and data bits during a Flash array read operation or that a Flash array read operation returning invalid data was attempted on a Flash block that was under a Flash command operation.¹ The SFDIF flag is cleared by writing a 1 to SFDIF. Writing a 0 to SFDIF has no effect on SFDIF. 0 No single bit fault detected 1 Single bit fault detected and corrected or a Flash array read operation returning invalid data was attempted operation returning invalid data was attempted while command running

Table 25-16. FERSTAT Field Descriptions

The single bit fault and double bit fault flags are mutually exclusive for parity errors (an ECC fault occurrence can be either single fault or double fault but never both). A simultaneous access collision (Flash array read operation returning invalid data attempted while command running) is indicated when both SFDIF and DFDIF flags are high.

² There is a one cycle delay in storing the ECC DFDIF and SFDIF fault flags in this register. At least one NOP is required after a flash memory read before checking FERSTAT for the occurrence of ECC errors.

25.3.2.9 P-Flash Protection Register (FPROT)

The FPROT register defines which P-Flash sectors are protected against program and erase operations.



Offset Module Base + 0x0008



¹ Loaded from IFR Flash configuration field, during reset sequence.

The (unreserved) bits of the FPROT register are writable with the restriction that the size of the protected region can only be increased (see Section 25.3.2.9.1, "P-Flash Protection Restrictions," and Table 25-21).

During the reset sequence, the FPROT register is loaded with the contents of the P-Flash protection byte in the Flash configuration field at global address 0x3_FF0C located in P-Flash memory (see Table 25-4) as indicated by reset condition 'F' in Figure 25-13. To change the P-Flash protection that will be loaded during the reset sequence, the upper sector of the P-Flash memory must be unprotected, then the P-Flash protection byte must be reprogrammed. If a double bit fault is detected while reading the P-Flash phrase containing the P-Flash protection byte during the reset sequence, the FPOPEN bit will be cleared and remaining bits in the FPROT register will be set to leave the P-Flash memory fully protected.

32 KByte Flash Module (S12FTMRG32K1V1)

48 KByte Flash Module (S12FTMRG48K1V1)

26.4.8 Wait Mode

The Flash module is not affected if the MCU enters wait mode. The Flash module can recover the MCU from wait via the CCIF interrupt (see Section 26.4.7, "Interrupts").

26.4.9 Stop Mode

If a Flash command is active (CCIF = 0) when the MCU requests stop mode, the current Flash operation will be completed before the MCU is allowed to enter stop mode.

26.5 Security

The Flash module provides security information to the MCU. The Flash security state is defined by the SEC bits of the FSEC register (see Table 26-11). During reset, the Flash module initializes the FSEC register using data read from the security byte of the Flash configuration field at global address 0x3_FF0F. The security state out of reset can be permanently changed by programming the security byte assuming that the MCU is starting from a mode where the necessary P-Flash erase and program commands are available and that the upper region of the P-Flash is unprotected. If the Flash security byte is successfully programmed, its new value will take affect after the next MCU reset.

The following subsections describe these security-related subjects:

- Unsecuring the MCU using Backdoor Key Access
- Unsecuring the MCU in Special Single Chip Mode using BDM
- Mode and Security Effects on Flash Command Availability

26.5.1 Unsecuring the MCU using Backdoor Key Access

The MCU may be unsecured by using the backdoor key access feature which requires knowledge of the contents of the backdoor keys (four 16-bit words programmed at addresses 0x3_FF00-0x3_FF07). If the KEYEN[1:0] bits are in the enabled state (see Section 26.3.2.2), the Verify Backdoor Access Key command (see Section 26.4.6.11) allows the user to present four prospective keys for comparison to the keys stored in the Flash memory via the Memory Controller. If the keys presented in the Verify Backdoor Access Key command match the backdoor keys stored in the Flash memory, the SEC bits in the FSEC register (see Table 26-11) will be changed to unsecure the MCU. Key values of 0x0000 and 0xFFFF are not permitted as backdoor keys. While the Verify Backdoor Access Key command is active, P-Flash memory and EEPROM memory will not be available for read access and will return invalid data.

96 KByte Flash Module (S12FTMRG96K1V1)

28.3.2.5 Flash Configuration Register (FCNFG)

The FCNFG register enables the Flash command complete interrupt and forces ECC faults on Flash array read access from the CPU.



Figure 28-9. Flash Configuration Register (FCNFG)

CCIE, IGNSF, FDFD, and FSFD bits are readable and writable while remaining bits read 0 and are not writable.

Field	Description
7 CCIE	 Command Complete Interrupt Enable — The CCIE bit controls interrupt generation when a Flash command has completed. 0 Command complete interrupt disabled 1 An interrupt will be requested whenever the CCIF flag in the FSTAT register is set (see Section 28.3.2.7)
4 IGNSF	 Ignore Single Bit Fault — The IGNSF controls single bit fault reporting in the FERSTAT register (see Section 28.3.2.8). 0 All single bit faults detected during array reads are reported 1 Single bit faults detected during array reads are not reported and the single bit fault interrupt will not be generated
1 FDFD	 Force Double Bit Fault Detect — The FDFD bit allows the user to simulate a double bit fault during Flash array read operations and check the associated interrupt routine. The FDFD bit is cleared by writing a 0 to FDFD. 0 Flash array read operations will set the DFDIF flag in the FERSTAT register only if a double bit fault is detected 1 Any Flash array read operation will force the DFDIF flag in the FERSTAT register to be set (see Section 28.3.2.7) and an interrupt will be generated as long as the DFDIE interrupt enable in the FERCNFG register is set (see Section 28.3.2.6)
0 FSFD	 Force Single Bit Fault Detect — The FSFD bit allows the user to simulate a single bit fault during Flash array read operations and check the associated interrupt routine. The FSFD bit is cleared by writing a 0 to FSFD. 0 Flash array read operations will set the SFDIF flag in the FERSTAT register only if a single bit fault is detected 1 Flash array read operation will force the SFDIF flag in the FERSTAT register to be set (see Section 28.3.2.7) and an interrupt will be generated as long as the SFDIE interrupt enable in the FERCNFG register is set (see Section 28.3.2.6)

Table 28-13. FCNFG Field Descriptions

28.3.2.6 Flash Error Configuration Register (FERCNFG)

The FERCNFG register enables the Flash error interrupts for the FERSTAT flags.

Chapter 30 192 KByte Flash Module (S12FTMRG192K2V1)

Revision Number	Revision Date	Sections Affected	Description of Changes
V01.06	23 Jun 2010	30.4.6.2/30-110 7 30.4.6.12/30-11 14 30.4.6.13/30-11 15	Updated description of the commands RD1BLK, MLOADU and MLOADF
V01.07	20 aug 2010	30.4.6.2/30-110 7 30.4.6.12/30-11 14 30.4.6.13/30-11 15	Updated description of the commands RD1BLK, MLOADU and MLOADF
Rev.1.27	31 Jan 2011	30.3.2.9/30-109 0	Updated description of protection on Section 30.3.2.9

Table 30-1. Revision History

30.1 Introduction

The FTMRG192K2 module implements the following:

- 192Kbytes of P-Flash (Program Flash) memory
- 4Kbytes of EEPROM memory

The Flash memory is ideal for single-supply applications allowing for field reprogramming without requiring external high voltage sources for program or erase operations. The Flash module includes a memory controller that executes commands to modify Flash memory contents. The user interface to the memory controller consists of the indexed Flash Common Command Object (FCCOB) register which is written to with the command, global address, data, and any required command parameters. The memory controller must complete the execution of a command before the FCCOB register can be written to with a new command.

CAUTION

A Flash word or phrase must be in the erased state before being programmed. Cumulative programming of bits within a Flash word or phrase is not allowed.





Table 31-5. Program IFR Fields

Global Address	Size (Bytes)	Field Description
0x0_4000 - 0x0_4007	8	Reserved
0x0_4008 – 0x0_40B5	174	Reserved
0x0_40B6 - 0x0_40B7	2	Version ID ¹

CCOBIX[2:0]	FCCOB Parameters		
000	0x03	Global address [17:16] of a P-Flash block	
001	Global address [15:0] of th	e first phrase to be verified	
010	Number of phras	ses to be verified	

 Table 31-36. Erase Verify P-Flash Section Command FCCOB Requirements

Upon clearing CCIF to launch the Erase Verify P-Flash Section command, the Memory Controller will verify the selected section of Flash memory is erased. The CCIF flag will set after the Erase Verify P-Flash Section operation has completed. If the section is not erased, it means blank check failed, both MGSTAT bits will be set.

Table 31-37. Erase Verify P-Flash Section Command Error Handling

Register	Error Bit	Error Condition
		Set if CCOBIX[2:0] != 010 at command launch
		Set if command not available in current mode (see Table 31-27)
	ACCERR	Set if an invalid global address [17:0] is supplied see Table 31-3)
		Set if a misaligned phrase address is supplied (global address [2:0] != 000)
FSTAT		Set if the requested section crosses a the P-Flash address boundary
	FPVIOL	None
	MGSTAT1	Set if any errors have been encountered during the read or if blank check failed.
	MGSTAT0	Set if any non-correctable errors have been encountered during the read or if blank check failed.

31.4.6.4 Read Once Command

The Read Once command provides read access to a reserved 64 byte field (8 phrases) located in the nonvolatile information register of P-Flash. The Read Once field is programmed using the Program Once command described in Section 31.4.6.6. The Read Once command must not be executed from the Flash block containing the Program Once reserved field to avoid code runaway.

CCOBIX[2:0]	FCCOB Parameters			
000	0x04	Not Required		
001	Read Once phrase inc	Read Once phrase index (0x0000 - 0x0007)		
010	Read Once word 0 value			
011	Read Once word 1 value			
100	Read Once word 2 value			
101	Read Once word 3 value			

Electrical Characteristics

Version Number	Revision Date	Description of Changes
Rev 0.49	5-Jun-2013	 Updated Section A.1.1, "Parameter Classification" Applied new M-parameter tag in Table A-7, Table A-9, Table A-11, Table A-16, Table A-22, Table A-24, Table A-26, Table A-28, Table A-32, Table A-43, Table A-45, and Table A-48 Updated Table A-39 (Num 2b, 6b)
Rev 0.50	15-Jul-2013	 Updated Section A.7, "NVM" (format and timing parameters)
Rev 0.51	23-Oct-2017	 Updated mask set condition in Table A-44 (Num 7a, 7b, 8a, 8b) Updated mask set condition in Table A-45 (Num 7a, 7b, 8a, 8b)

A.1 General

This supplement contains the most accurate electrical information for the MC9S12G microcontroller available at the time of publication.

This introduction is intended to give an overview on several common topics like power supply, current injection etc.

A.1.1 Parameter Classification

The electrical parameters shown in this supplement are guaranteed by various methods. To give the customer a better understanding the following classification is used and the parameters are tagged accordingly in the tables where appropriate.

NOTE

This classification is shown in the column labeled "C" in the parameter tables where appropriate.

- P: Those parameters are guaranteed during production testing on each individual device.
- M: These parameters are characterized at 160°C and tested in production at an ambient temperature of 150°C with appropriate guardbanding to guarantee operation at 160°C.
- C: Those parameters are achieved by the design characterization by measuring a statistically relevant sample size across process variations.
- T: Those parameters are achieved by design characterization on a small sample size from typical devices under typical conditions unless otherwise noted. All values shown in the typical column are within this category.
- D: Those parameters are derived mainly from simulations.

A.1.2 Power Supply

The VDDA, VSSA pin pairs supply the A/D converter and parts of the internal voltage regulator.

The VDDX, VSSX pin pairs [3:1] supply the I/O pins.

VDDR supplies the internal voltage regulator.

The VDDF, VSS1 pin pair supplies the internal NVM logic.

Package and Die Information

D.1 100 LQFP Mechanical Dimensions



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